

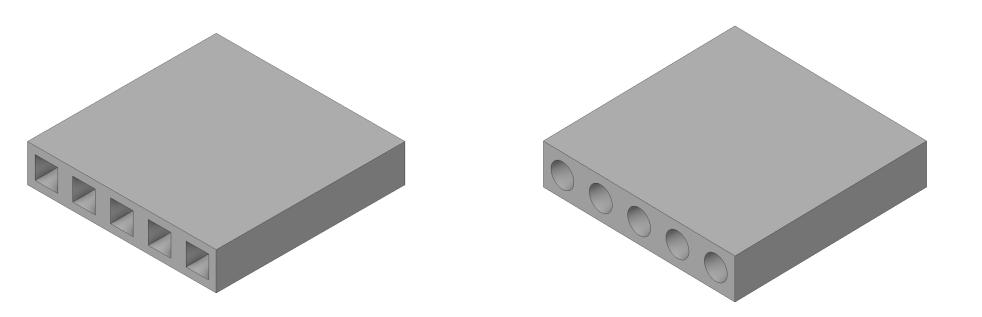


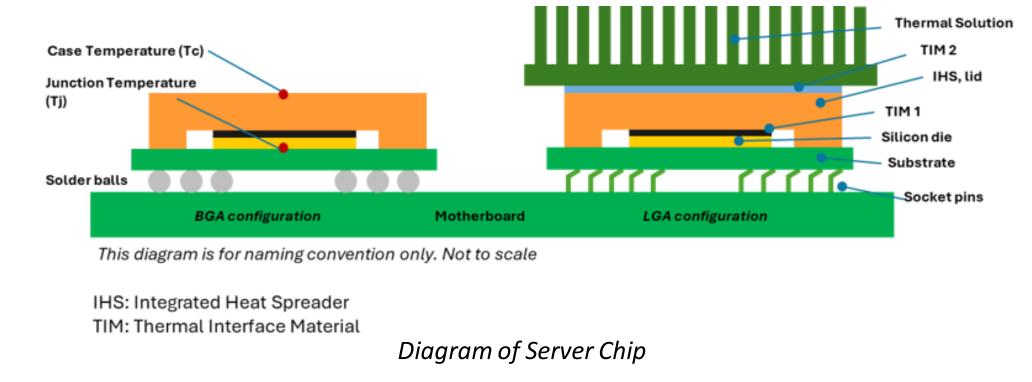
Bifacial Coldplates for High Power Servers

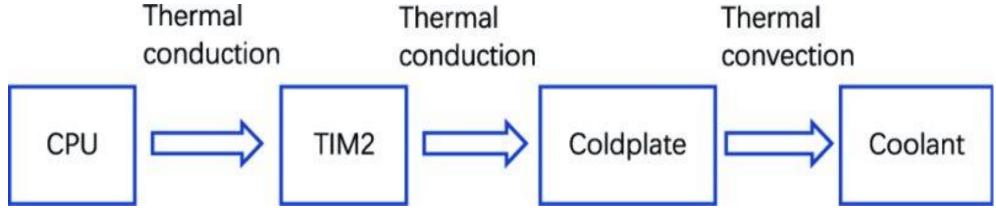
Project Description:

Our team will simulate, build, and test different designs of a new coldplate for the Microsoft high powered servers that will be used in a water-cooled system. The development of the new coldplate to keep the case operating temperature at **80°C** (176°F) due to the intense heat caused by the server chip input power of **1000W**. Other design necessities include corrosion resistance and ability to uphold electronics functions.







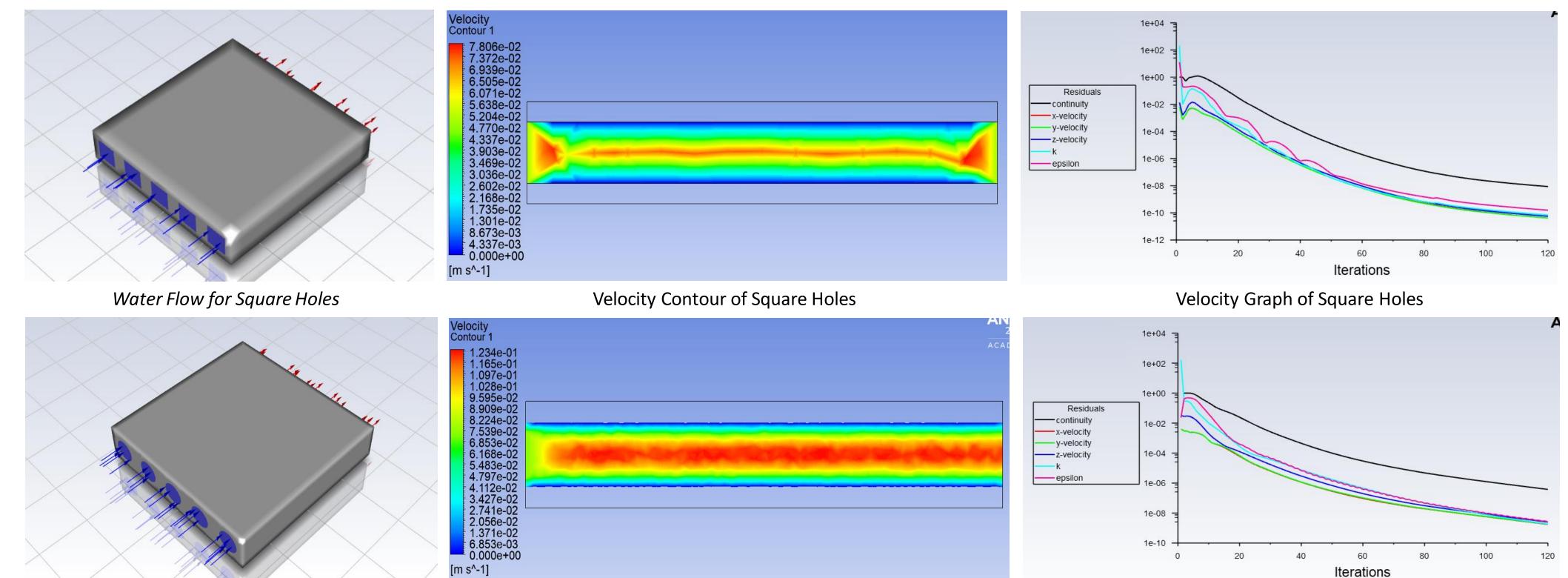


Path of Heat Transfer

Possible solutions-

- 1. Structure and Sizing
 - Material has not yet been decided as further testing is required •
 - Server chip is 50mm x 50mm therefore the coldplate should be around those dimensions

- Design Option 1: Square Holes
- Design Option 2: Circular Holes
- Keep-out zone (KOZ) of 65mm x 65mm surrounding the server chip •
- 2. Temperature
 - Inlet temperature of 40°C
 - Desired component case temperature of 80° ۲
- 3. Water Flow
 - Inlet water velocity range of 1 2.5 lpm
 - Target of 1.5 lpm per kW

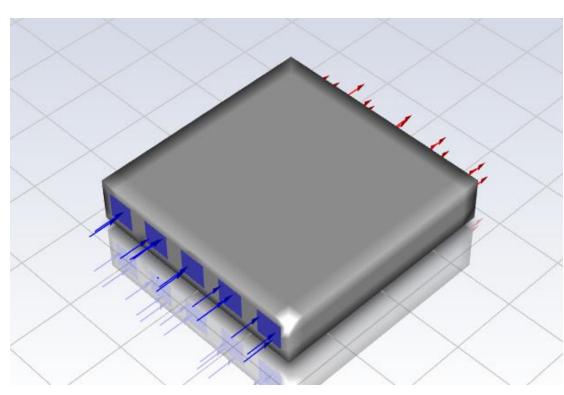


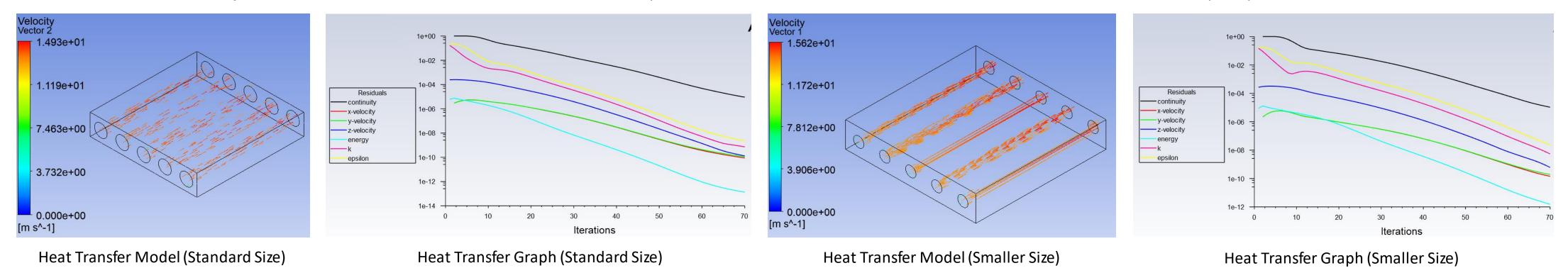
Water Flow for Circular Holes

Velocity Contour of Circular Holes

Velocity Graph of Circular Holes

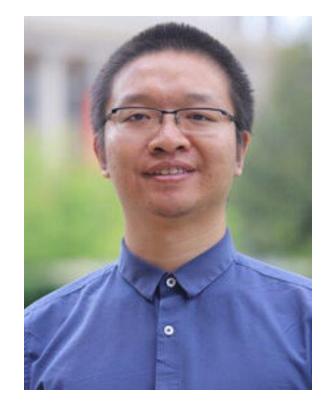
ANSYS Test Simulations:





Deliverables:

- Models and simulations of server chip in water-cooled designs
- 2. Manufacturing of multiple iterations of prototypes
- Prototype testing with assistance from Microsoft's testing facilities using chillers with pumps 3.
- Produce a cold plate that reduces case temperature to 80°C 4.



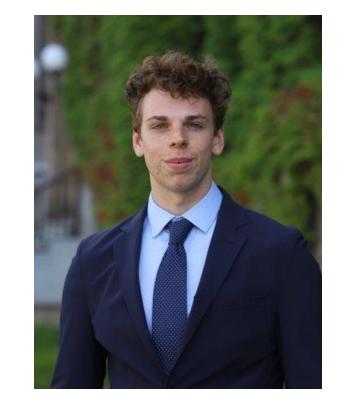
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